



Product Specification

Part Name: 0.48 inch PMOLED Display Module

Customer Part ID:

Topovision Part ID: TVO7232A

Ver: A

Customer:
Approved by

From: Topovision Technology Co., Ltd.
Approved by

Notes:

1. Please contact Topovision Technology Co., Ltd. before assigning your product based on this module specification
2. The information contained herein is presented merely to indicate the characteristics and performance of our products. No responsibility is assumed by Topovision Technology Co., Ltd. for any intellectual property claims or other problems that may result from application based on the module described herein.

Contents

REVISION HISTORY	3
1. GENERAL DESCRIPTION	4
1.1 DESCRIPTION.....	4
1.2 GENERAL INFORMATION.....	4
2. ABSOLUTE MAXIMUM RATING	5
3. ELECTRICAL CHARACTERISTICS	6
4. MODULE OUTLINE DIMENSION	9
5. MODULE INTERFACE DESCRIPTION	10
6. REFERENCE APPLICATION CIRCUIT	13
7. TIMINGS FOR SPI Interface	14
8. RELIABILITY TEST CONDITIONS	16
9. PACKING	17
10. APPENDIXES	17

1. GENERAL DESCRIPTION

1.1 DESCRIPTION

- Small molecular organic light emitting diode.
- Color : White
- Panel resolution : 72*32
- Driver IC : SPD0301
- Excellent Quick response time : 10 μ s
- Extremely thin thickness for best mechanism design : 1.21 mm
- High contrast : 2000:1
- Wide viewing angle : 160°
- Serial Peripheral Interface
- Wide range of operating temperature : -40 to 70 °C
- Anti-glare polarizer.

1.2 GENERAL INFORMATION

NO	ITEM	SPECIFICATION	UNIT
1	Dot Matrix	72 x 32	dot
2	Dot Size	0.136 (W) x 0.136 (H)	mm ²
3	Dot Pitch	0.156 (W) x 0.156 (H)	mm ²
4	Aperture Rate	76	%
5	Active Area	11.212 (W) x 4.972 (H)	mm ²
6	Panel Size	14.9 (W) x 11.29 (H)	mm ²
7*	Panel Thickness	1.02 \pm 0.05	mm
8	Module Size	14.9 (W) x 22.29 (H) x 1.21 (T)	mm ³
9	Diagonal A/A size	0.48	inch
10	Module Weight	TBD	gram

* Panel thickness includes substrate glass, cover glass and UV glue thickness.

2. ABSOLUTE MAXIMUM RATING

ITEM	MIN	MAX	UNIT	Condition	Remark
Supply Voltage (V_{DD})	-0.3	4	V	Ta = 25 °C	IC maximum rating
Supply Voltage (V_{CC})	8	17	V	Ta = 25 °C	IC maximum rating
Operating Temp.	-40	70	°C		
Storage Temp	-40	85	°C		
Humidity	-	85	%		
Life Time	13,000	-	Hrs	220 cd/m ² , 50% checkerboard	Note (1)
Life Time	15,000	-	Hrs	200 cd/m ² , 50% checkerboard	Note (2)
Life Time	16,000	-	Hrs	180 cd/m ² , 50% checkerboard	Note (3)

Note:

- (A) Under $V_{CC} = 13V$
 - (B) Life time is defined the amount of time when the luminance has decayed to less than 50% of the initial measured luminance.
 - (C) Note (1), Note (2), Note (3) contrast setting are under $V_{DD}=2.8V$, set VDD selection (0xad)=(0x40) and $V_{DD}=1.8V$, set VDD selection (0xad)=(0x60).
- (1) Setting of 220 cd/m² :
- Contrast setting : 0x44
 - Frame rate : 105Hz
 - Duty setting : 1/32
- (2) Setting of 200 cd/m² :
- Contrast setting : 0x3e
 - Frame rate : 105Hz
 - Duty setting : 1/32
- (3) Setting of 180 cd/m² :
- Contrast setting : 0x37
 - Frame rate : 105Hz
 - Duty setting : 1/32

3. ELECTRICAL CHARACTERISTICS

3.1 D.C ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITION	MIN	TYP	MAX	UNIT
V _{CC}	Operating Voltage	-	12.5	13	13.5	V
V _{DD}	Logic Supply Voltage	-	1.7	1.8	1.9	V
			2.7	2.8	2.9	
V _{OH}	High Logic Output Level	I _{OUT} = 100uA, 3.3MHz	0.9* V _{DD}	-	-	V
V _{OL}	Low Logic Output Level	I _{OUT} = 100uA, 3.3MHz	-	-	0.1*V _{DD}	V
V _{IH}	High Logic Input Level	-	0.8* V _{DD}	-	-	V
V _{IL}	Low Logic Input Level	-	-	-	0.2*V _{DD}	V
I _{DD, SLEEP}	Sleep mode Current	V _{DD} = 1.65V~3.3V, V _{CC} = 7V~16V Display OFF, No panel attached	-	-	10	uA
I _{CC, SLEEP}	Sleep mode Current	V _{DD} = 1.65V~3.3V, V _{CC} = 7V~16V Display OFF, No panel attached	-	-	10	uA
I _{CC}	V _{CC} Supply Current V _{DD} = 2.8V, V _{CC} = 12, I _{REF} = 10uA, No Panel attached, Display ON, All ON	Contrast = FFh	-	450	580	uA
			I _{DD}	V _{DD} Supply Current V _{DD} = 2.8V, V _{CC} = 12, I _{REF} = 10uA, No Panel attached, Display ON, All ON,	-	90
I _{SEG}	Segment Output Current, V _{DD} = 2.8V, V _{CC} = 12V, I _{REF} = 10uA, Display ON.	Contrast=FFh	280	310	340	uA
		Contrast=AFh	-	215	-	
		Contrast=7Fh	-	155	-	
		Contrast=3Fh	-	78	-	
		Contrast=0Fh	-	20	-	

PANEL ELECTRICAL SPECIFICATIONS

PARAMETER	MIN	TYP.	MAX	UNITS	COMMENTS
Normal mode current consumption	-	5.5	7.5	mA	All pixels on
Standby mode current consumption	-	0.5	1.5	mA	Standby mode 10% pixels on
Normal mode power consumption	-	71.5	97.5	mW	All pixels on
Standby mode power consumption	-	6.5	19.5	mW	Standby mode 10% pixels on
Pixel Luminance	180	200		cd/m ²	Display Average
Standby Luminance		25		cd/m ²	
CIE _x (White)	0.24	0.28	0.32		CIE1931
CIE _y (White)	0.28	0.32	0.36		CIE1931
Dark Room Contrast	2000:1				
Viewing Angle	160			degree	
Response Time		10		μs	

Note:

VDD is 2.8V, set VDD selection (0xad)=(0x40),

VDD is 1.8V, set VDD selection (0xad)=(0x60) contrast setting is shown below.

(1) Normal mode condition :

- Driving Voltage : 13V
- Contrast setting : 0x3e
- Frame rate : 105Hz
- Duty setting : 1/32

(2) Standby mode condition :

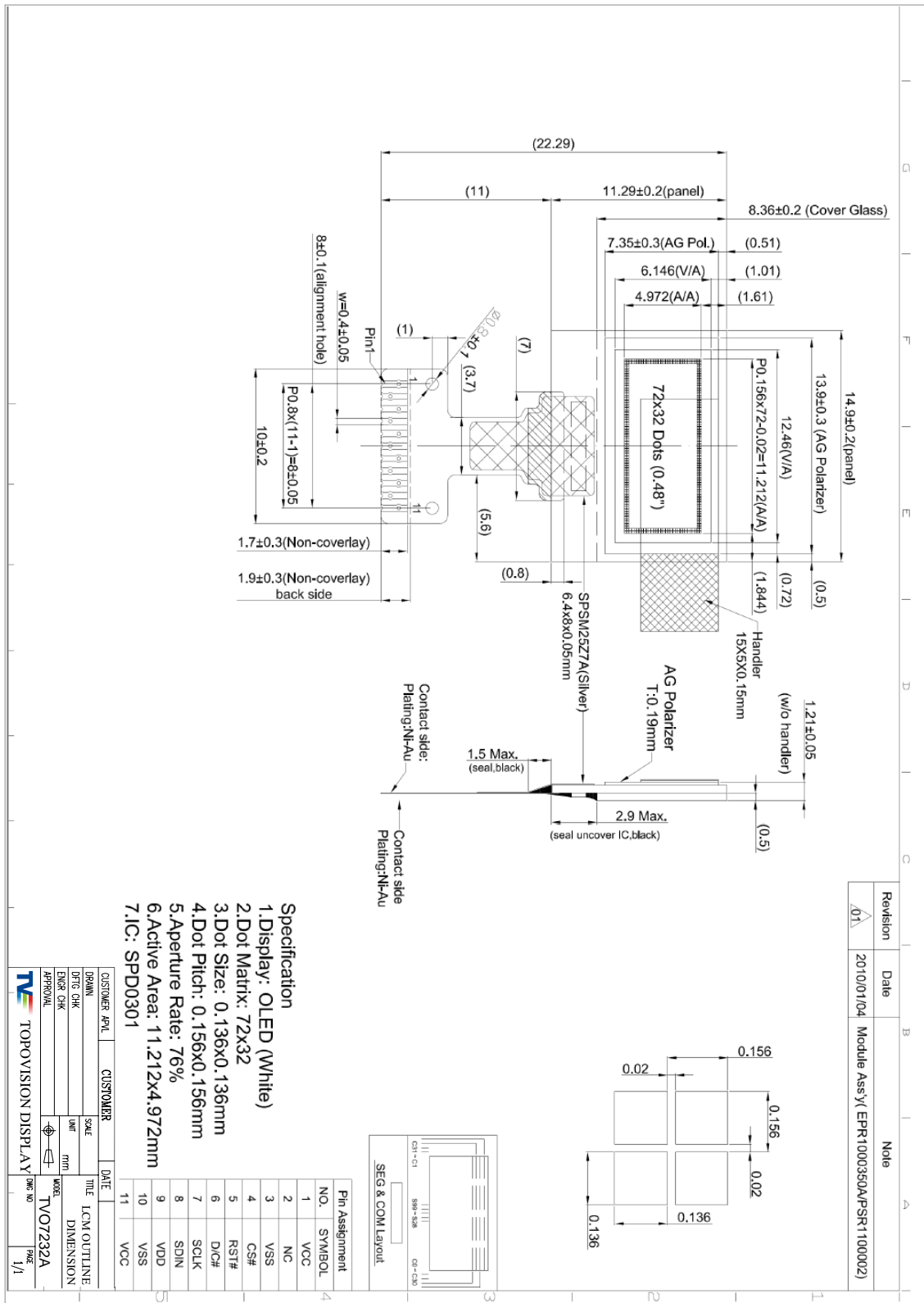
- Driving Voltage : 13V
- Contrast setting : 0x00
- Frame rate : 105Hz
- Duty setting : 1/32

VDD(Logic Supply Voltage):1.8V and 2.8V setting

Brightness(cd/m2)	VDD(V)	Set VDD selection (0xad)	Dot matrix current level (0x81)
25 (Standby mode)	2.8	0x40	0x00
180 (Minimum mode)	2.8	0x40	0x37
200 (Typical mode)	2.8	0x40	0x3e
220 (Maximum mode)	2.8	0x40	0x44

Brightness(cd/m2)	VDD(V)	Set VDD selection (0xad)	Dot matrix current level (0x81)
25 (Standby mode)	1.8	0x60	0x00
180 (Minimum mode)	1.8	0x60	0x37
200 (Typical mode)	1.8	0x60	0x3e
220 (Maximum mode)	1.8	0x60	0x44

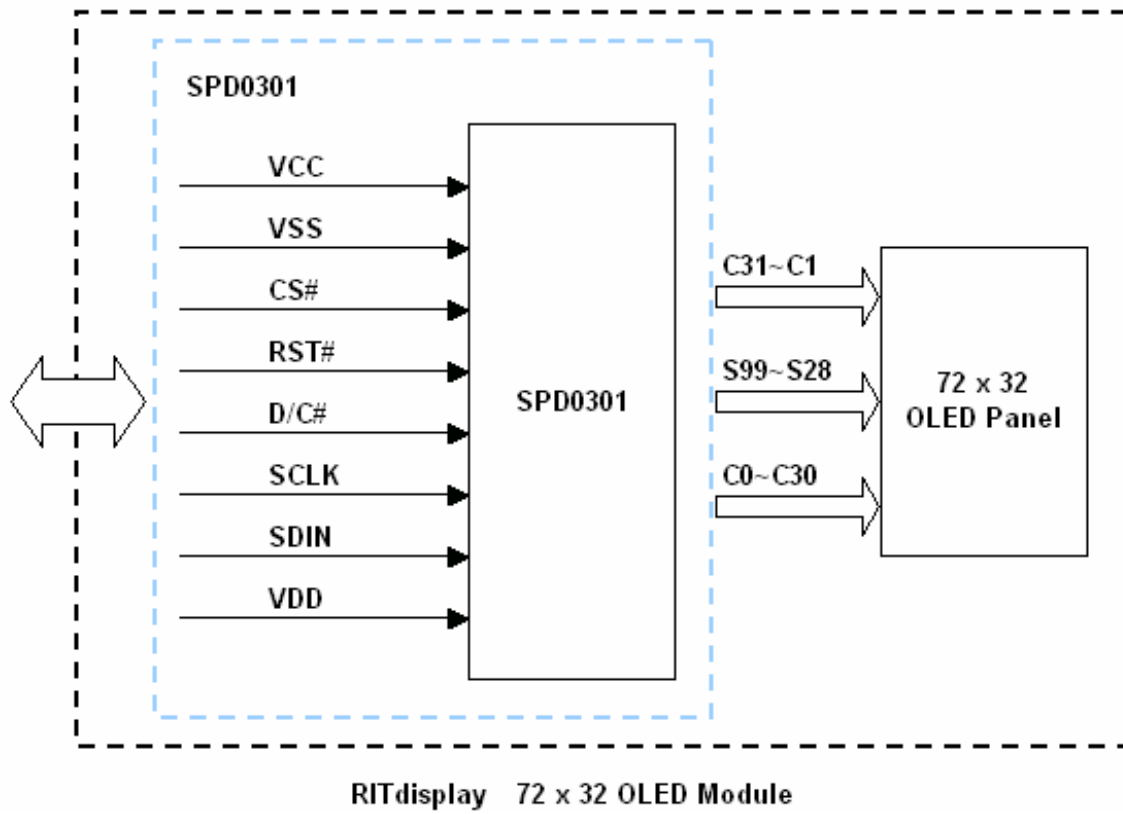
4. MODULE OUTLINE DIMENSION



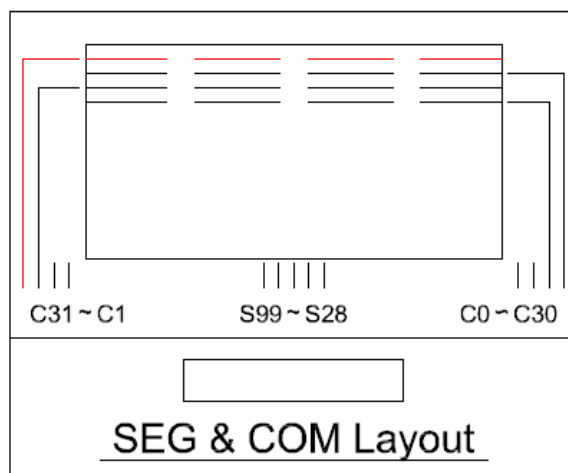
5. MODULE INTERFACE DESCRIPTION

PIN NO	PIN NAME	DESCRIPTION
1	VCC	Power supply for panel driving voltage.
2	NC	This is dummy pin. Do not group or short NC pins together.
3	VSS	Ground pin. It must be connected to external ground.
4	CS#	This pin is the chip select input connecting to the MCU. The chip is enabled for MCU communication only when CS# is pulled LOW (active LOW).
5	RST#	This pin is reset signal input. When the pin is pulled LOW, initialization of the chip is executed. Keep this pin pull HIGH during normal operation.
6	D/C#	This pin is Data/Command control pin connecting to the MCU.
7	SCLK	These pins are bi-directional data bus connecting to the MCU data bus.
8	SDIN	When serial interface mode is selected, D0 will be the serial clock input: SCLK; D1 will be the serial data input: SDIN.
9	VDD	Power supply pin for core logic operation.
10	VSS	Ground pin. It must be connected to external ground.
11	VCC	Power supply for panel driving voltage.

5.1 FUNCTION BLOCK DIAGRAM



5.2 PANEL LAYOUT DIAGRAM



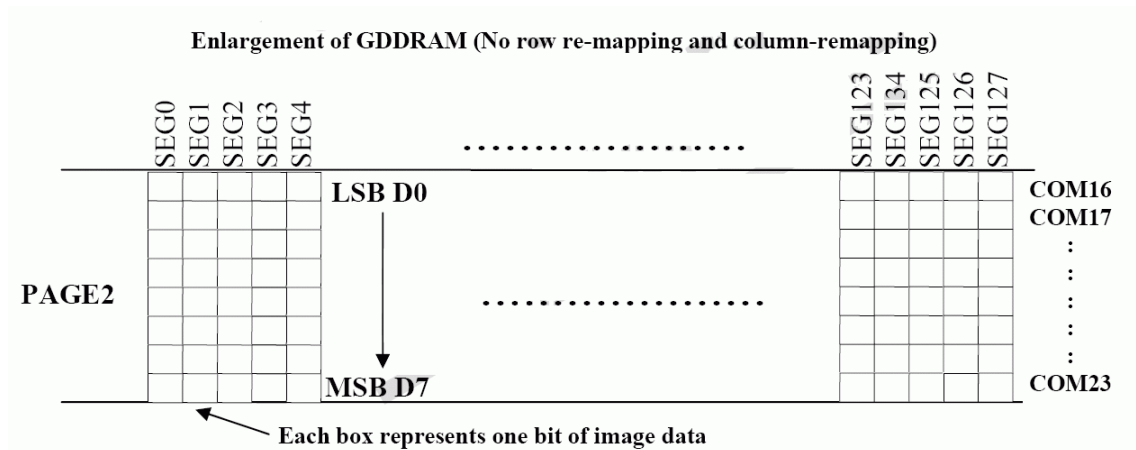
5.3 Graphic Display Data Ram Address Map

The GDDRAM is a bit mapped static RAM holding the bit pattern to be displayed. The size of the RAM is 128 x 64 bits and the RAM is divided into eight pages, from PAGE0 to PAGE7, which are used for monochrome 128x64 dot matrix display, as shown in below figures.

GDDRAM pages structure of SPD0301

		Row re-mapping
PAGE0 (COM0-COM7)	Page 0	PAGE0 (COM 63-COM56)
PAGE1 (COM8-COM15)	Page 1	PAGE1 (COM 55-COM48)
PAGE2 (COM16-COM23)	Page 2	PAGE2 (COM47-COM40)
PAGE3 (COM24-COM31)	Page 3	PAGE3 (COM39-COM32)
PAGE4 (COM32-COM39)	Page 4	PAGE4 (COM31-COM24)
PAGE5 (COM40-COM47)	Page 5	PAGE5 (COM23-COM16)
PAGE6 (COM48-COM55)	Page 6	PAGE6 (COM15-COM8)
PAGE7 (COM56-COM63)	Page 7	PAGE7 (COM 7-COM0)
	SEG0 -----SEG127	
Column re-mapping	SEG127 -----SEG0	

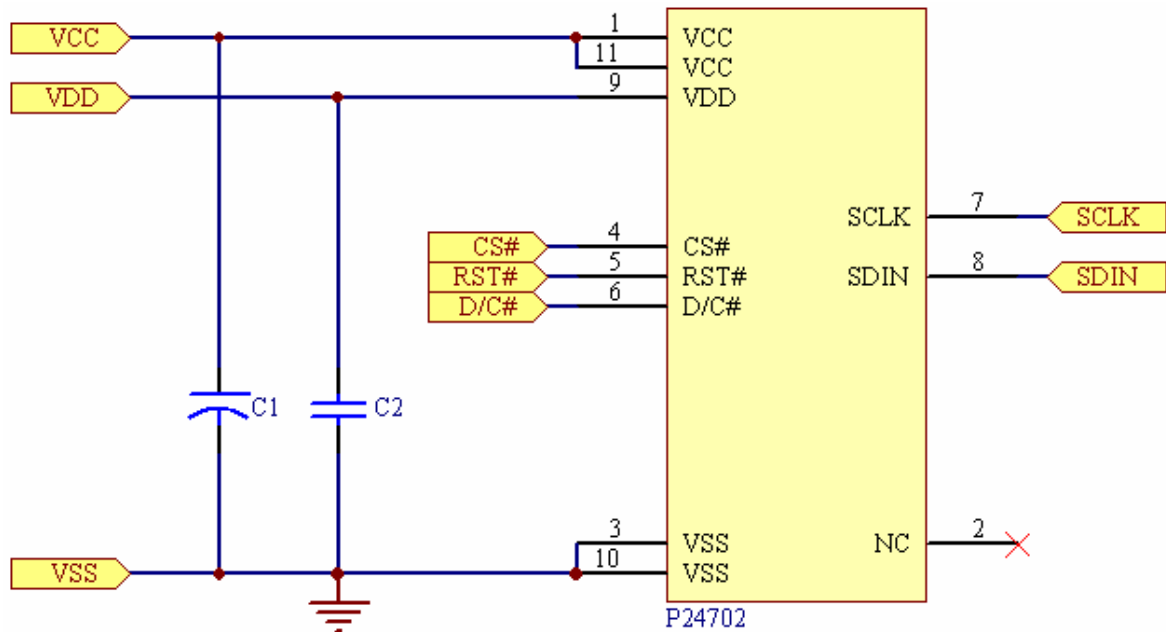
When one data byte is written into GDDRAM, all the rows image data of the same page of the current column are filled (i.e. the whole column (8 bits) pointed by the column address pointer is filled.). Data bit D0 is written into the top row, while data bit D7 is written into bottom row as shown in below figures.



For mechanical flexibility, re-mapping on both Segment and Common outputs can be selected by software.

For vertical shifting of the display, an internal register storing the display start line can be set to control the portion of the RAM data to be mapped to the display (command D3h).

6. REFERENCE APPLICATION CIRCUIT



Recommend components :

C1 : 4.7uF/25V (Tantalum type) or VISHAY (572D475X0025A2T)

C2 : 1uF/16V (0603)

This circuit is designed for SPI interface.

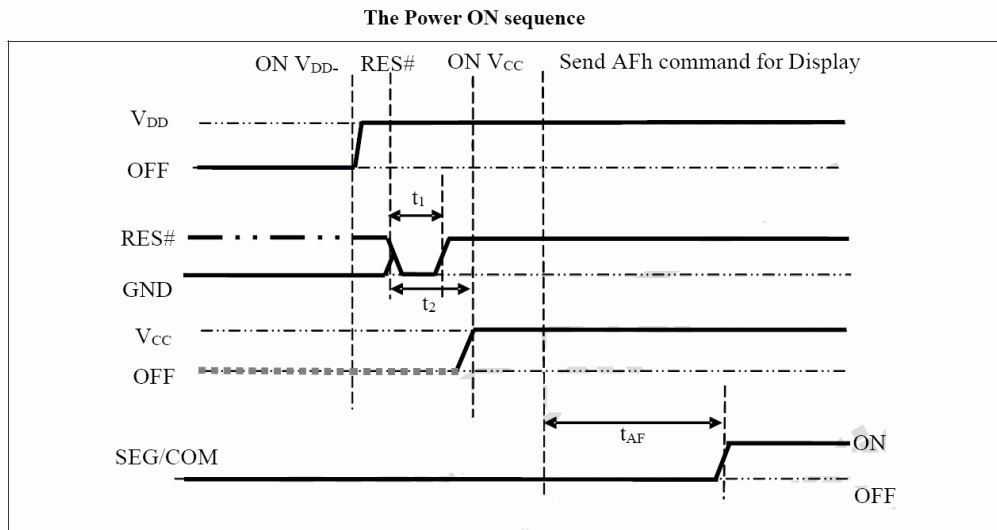
7. TIMINGS FOR SPI Interface

7.1 POWER ON/OFF SEQUENCE

The following figures illustrate the recommended power ON and power OFF sequence of SPD0301

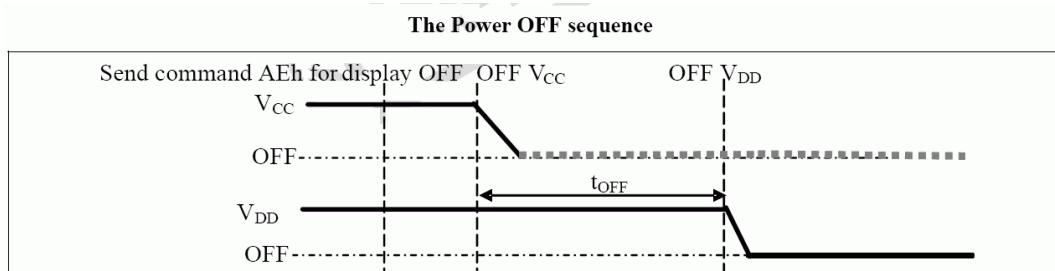
Power ON sequence:

1. Power ON V_{DD}
2. After V_{DD} become stable, set RES# pin LOW (logic low) for at least 3us (t_1)⁽³⁾ and then HIGH (logic high).
3. After set RES# pin LOW (logic low), wait for at least 3us (t_2). Then Power ON V_{CC} .⁽¹⁾
4. After V_{CC} become stable, send command AFh for display ON. SEG/COM will be ON after 100ms (t_{AF}).



Power OFF sequence:

1. Send command AEh for display OFF.
2. Power OFF V_{CC} ^{(1), (2)}
3. Power OFF V_{DD} after t_{OFF} .⁽⁴⁾ (where Minimum t_{OFF} =80ms, Typical t_{OFF} =100ms)



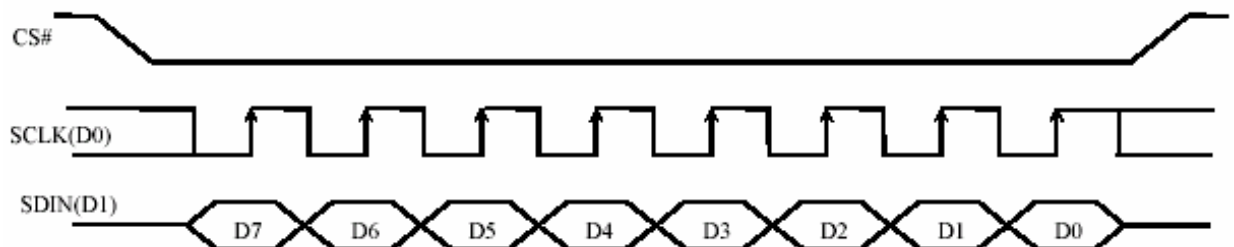
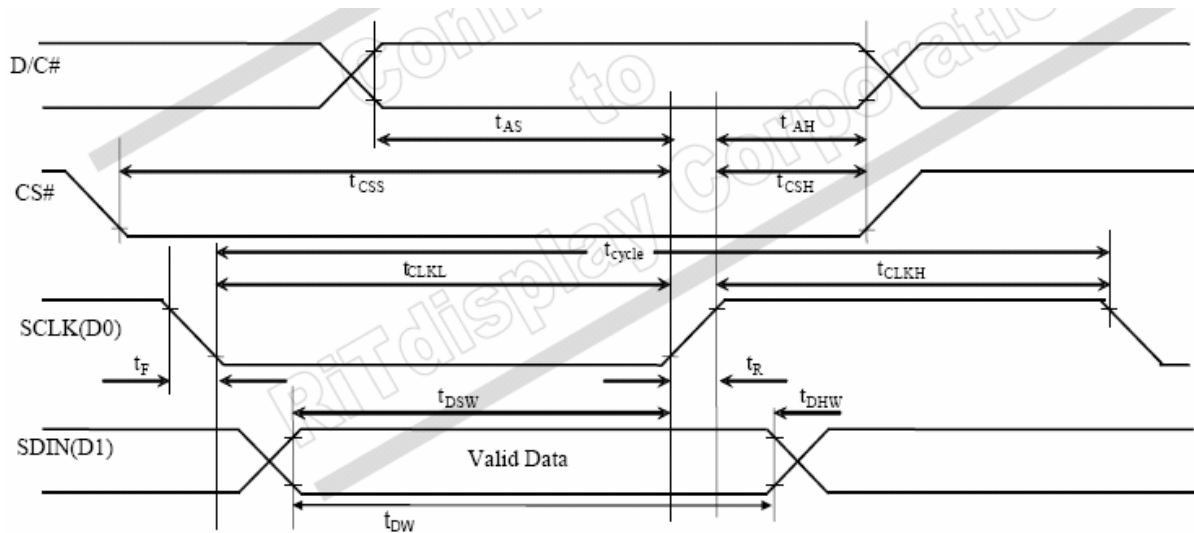
Note:

- (1) V_{CC} should be disabled when it is OFF.
- (2) Power Pins (V_{DD} , V_{CC}) can never be pulled to ground under any circumstance.
- (3) The register values are reset after t_1 .
- (4) V_{DD} should not be Power OFF before V_{CC} Power OFF.

SPI Interface Timing Characteristics.

($V_{DD} - V_{SS} = 1.65V \sim 3.3V$, $T_A = 25^\circ C$)

Symbol	Parameter	Min	Typ	Max	Unit
t_{cycle}	Clock Cycle Time	100	-	-	ns
t_{AS}	Address Setup Time	15	-	-	ns
t_{AH}	Address Hold Time	15	-	-	ns
t_{CSS}	Chip Select Setup Time	20	-	-	ns
t_{CSH}	Chip Select Hold Time	50	-	-	ns
t_{DW}	Data Write Time	55	-	-	ns
t_{DSW}	Write Data Setup Time	15	-	-	ns
t_{DHW}	Write Data Hold Time	15	-	-	ns
t_{CLKL}	Clock Low Time	50	-	-	ns
t_{CLKH}	Clock High Time	50	-	-	ns
t_R	Rise Time	-	-	40	ns
t_F	Fall Time	-	-	40	ns



8. RELIABILITY TEST CONDITIONS

No.	Items	Specification	Quantity
1	High temp. (Non-operation)	85 °C, 240hrs	5
2	High temp. (Operation)	70 °C, 120hrs	5
3	Low temp. (Operation)	-40 °C, 120hrs	5
4	High temp. / High humidity (Operation)	65 °C, 90%RH, 120hrs	5
5	Thermal shock (Non-operation)	-40 °C ~85 °C (-40 °C /30min; transit /3min; 85 °C /30min; transit /3min) 1cycle: 66min, 100 cycles	5
6	Vibration	Frequency : 5~50HZ, 0.5G Scan rate : 1 oct/min Time : 2 hrs/axis Test axis : X, Y, Z	1 Carton
7	Drop	Height: 120cm Sequence : 1 angle 、 3 edges and 6 faces Cycles: 1	1 Carton
8	ESD (Non-operation)	Air discharge model, ±8kV, 10 times	5

Test and measurement conditions

1. All measurements shall not be started until the specimens attain to temperature stability.
2. All-pixels-on is used as operation test pattern.
3. The degradation of Polarizer are ignored for item 1, 4 & 5.

Evaluation criteria

1. The function test is OK.
2. No observable defects.
3. Luminance: > 50% of initial value.
4. Current consumption: within \pm 50% of initial value.

9. PACKING SPECIFICATION

TBD.

10. APPENDIXES

APPENDIX 1: DEFINITIONS

A. DEFINITION OF CHROMATICITY COORDINATE

The chromaticity coordinate is defined as the coordinate value on the CIE 1931 color chart for R, G, B, W.

B. DEFINITION OF CONTRAST RATIO

The contrast ratio is defined as the following formula:

$$\text{Contrast Ratio} = \frac{\text{Luminance of all pixels on measurement}}{\text{Luminance of all pixels off measurement}}$$

C. DEFINITION OF RESPONSE TIME

The definition of turn-on response time T_r is the time interval between a pixel reaching 10% of steady state luminance and 90% of steady state luminance. The definition of turn-off response time T_f is the time interval between a pixel reaching 90% of steady state luminance and 10% of steady state luminance. It is shown in Figure 2.

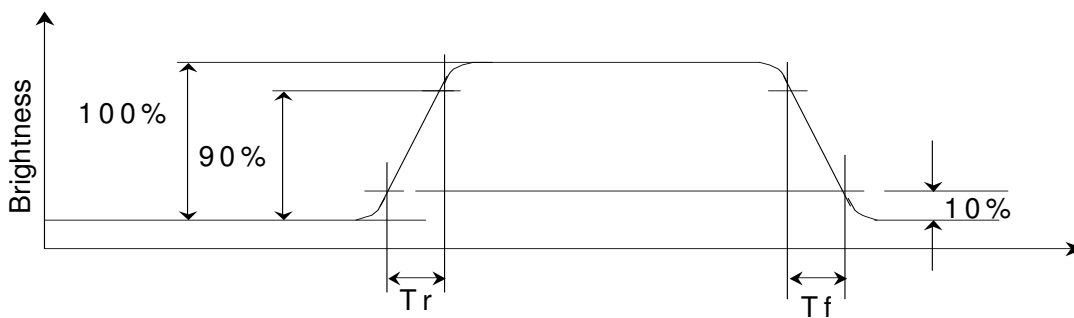


Figure 2 Response time

D. DEFINITION OF VIEWING ANGLE

The viewing angle is defined as Figure 3. Horizontal and vertical (H & V) angles are determined for viewing directions where luminance varies by 50% of the perpendicular value.

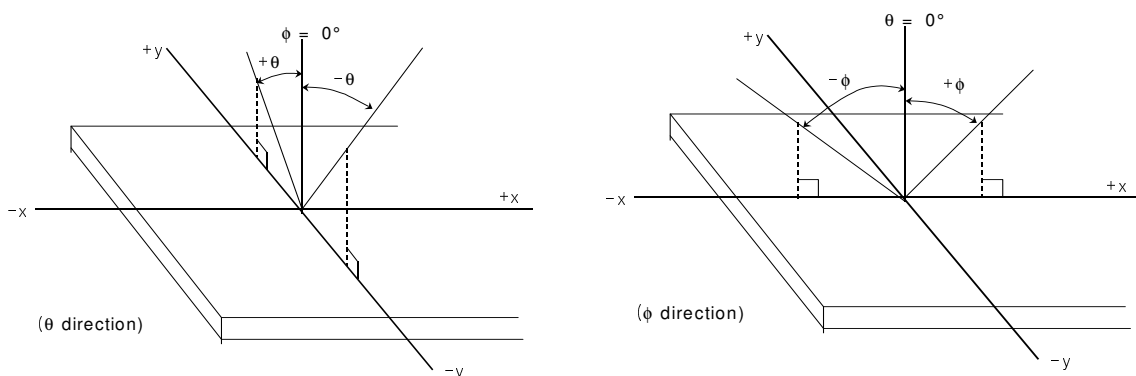
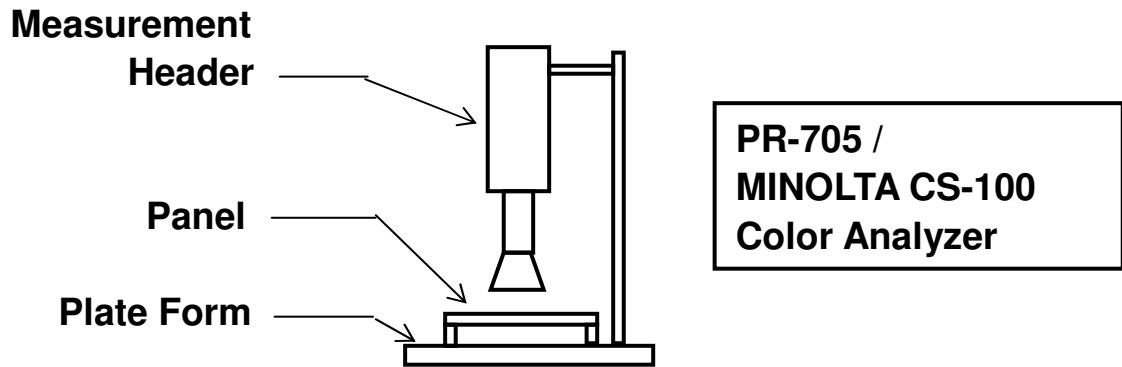


Figure 3 Viewing angle

APPENDIX 2: MEASUREMENT APPARATUS

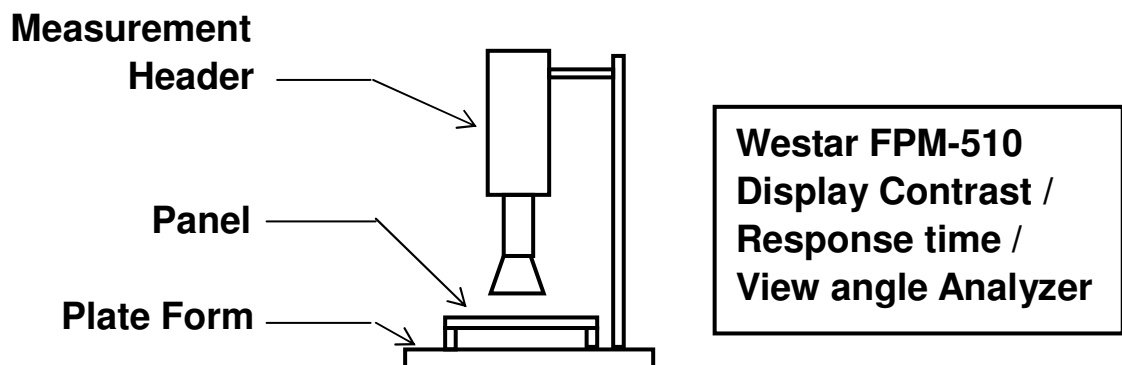
A. LUMINANCE/COLOR COORDINATE

PHOTO RESEARCH PR-705, MINOLTA CS-100

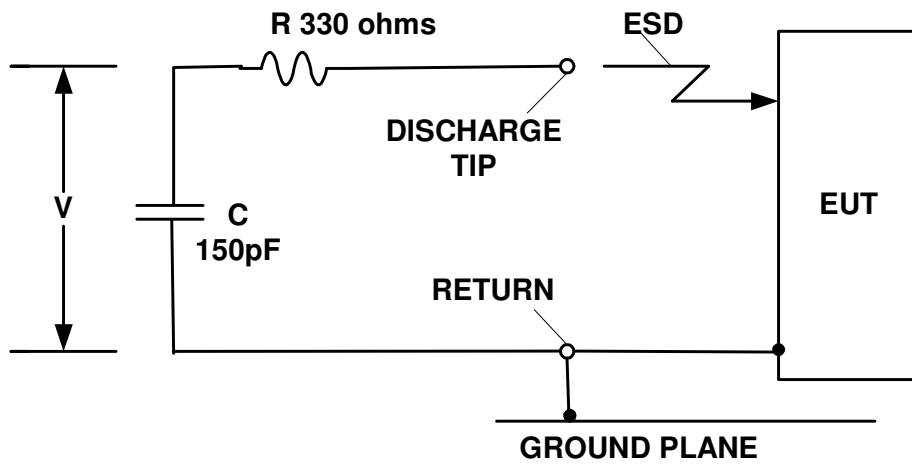


B. CONTRAST / RESPONSE TIME / VIEWING ANGLE

WESTAR CORPORATION FPM-510



C. ESD ON AIR DISCHARGE MODE



APPENDIX 3: PRECAUTIONS

A. RESIDUE IMAGE

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.